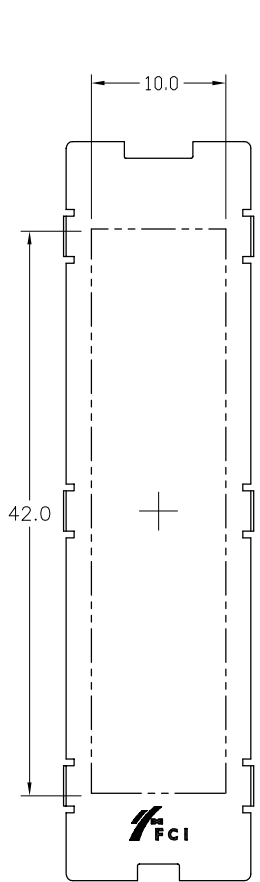


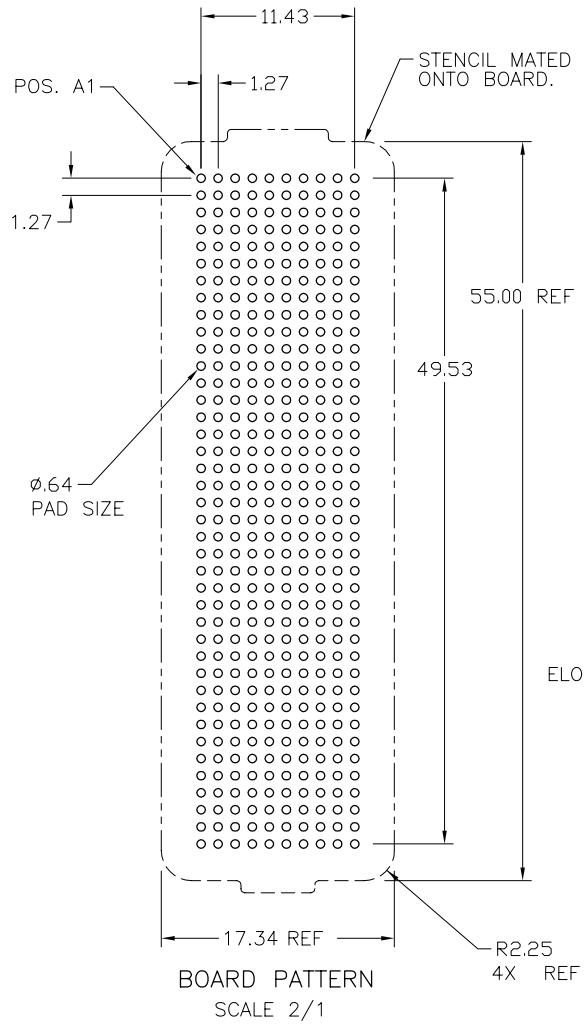
Ø.760 SOLDER BALLS
NOTE 2.
⊕ Ø.30 | X | Y

▱ .203

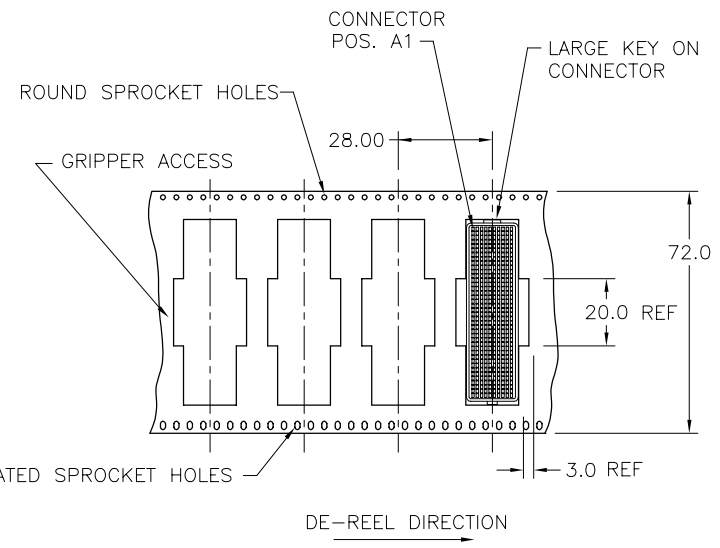
mat'l. code		SEE NOTE 1		surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection	product family	
ltr	ec'n no	dr	date	tolerances unless otherwise specified					title	MEG-ARRAY
N	V06-0560	LP	2006/07/18	angles	X+3	MM			4mm RECPT. ASSY	
-	-	-	-	line fit	XX+.13	scale 3:1			10 X 40= 400 POS.	
H	V00181	HLJ	7/5/00	0° ±2'	XXX+.051	FCI			sheet 1 of 3	
J	V20006	DRW	1/3/2	dr	D WAUGHEN	11.26.97	74221		size A4	
K	V03-0679	DAI	6/19/03	enr	T LEMKE	11.26.97	type		CUSTOMER Drawing	
L	V04-0940	VS	10/18/04	chr	T LEMKE	11.26.97				
M	V05-1071	DAI	12/21/05	appd	T LEMKE	11.26.97				
sheet index	revision sheet	N	N	N						
		1	2	3						



FLAT AREA FOR PICK-UP CAP



BOARD PATTERN SCALE 2/1



TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕-□	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title 4mm RECT. ASSY 10x40= 400 POS.
N				angles X*.3 .XX*.13 0° ±2'	scale 2:1
		dr	D WAUGHEN	11.26.97	
		enr	T LEMKE	11.26.97	
		chr	T LEMKE	11.26.97	
		appd	T LEMKE	11.26.97	
sheet index	revision sheet				dwg no 74221 sheet 2 of 3 size A4 type CUSTOMER Drawing

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74221-001	YES	15u" (.38um) Au OVER Ni	SnPb
74221-001LF			SnAgCu LEAD FREE (6)(7)
74221-101	YES	30 u" (.76um) Au OVER Ni	SnPb
74221-101LF			SnAgCu LEAD FREE (6)(7)
74221-201	YES	SEE NOTE 5.	SnPb
74221-201LF			SnAgCu LEAD FREE (6)(7)

NOTES:

1. MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET3)
 SOLDER BALL: (SEE TABLE ON SHEET3)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

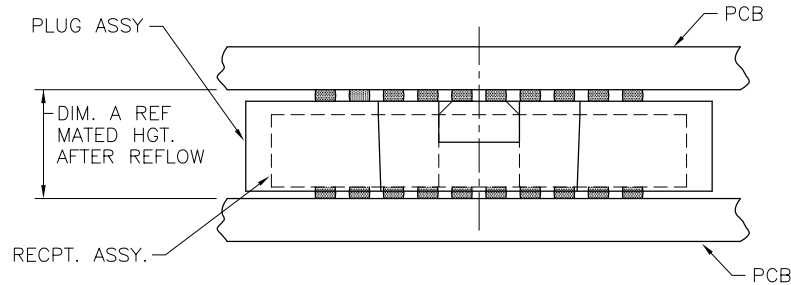
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

4. NO TIN\LEAD OR FLUX ABOVE TERMINAL SHOULDER.

5. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
4.0	84740	74221
10.0	84520	74221

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-ARRAY
ltr	ecr no	dr	date	title 4mm RECPT. ASSY 10x40= 400 POS.	
N				angles X*3 XX*13	scale 2:1
				0° ±2'	XXX*051
		dr	D WAUGHEN	11.26.97	FCI dwg no 74221 sheet 3 of 3 size A4 type CUSTOMER Drawing
		enr	T LEMKE	11.26.97	
		chr	T LEMKE	11.26.97	
		appd	T LEMKE	11.26.97	
sheet index	revision sheet				